

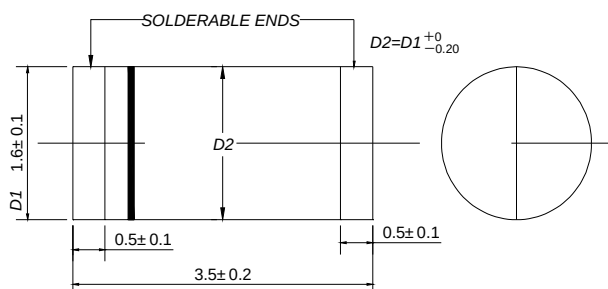

REVERSE VOLTAGE: 50 - 1000 V
CURRENT: 0.5A
DO - 213AA

Features

- ◇ Plastic package has underwriters laboratory flammability classifications
- ◇ For surface mounted applications
- ◇ Low profile package
- ◇ Built-in strain relief, ideal for automated placement
- ◇ Glass passivated chip junction
- ◇ High temperature soldering: 250°C/10 seconds at terminals

Mechanical Data

- ◇ Case: JEDEC DO-213AA, molded plastic over passivated chip
- ◇ Polarity: Color band denotes cathode end
- ◇ Weight: 0.0014 ounces, 0.036 gram



Dimensions in millimeters

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified

		GL34A	GL34B	GL34D	GL34G	GL34J	GL34K	GL34M	UNITS
Polarity color bands (2nd Band)		Gray	Red	Orange	Yellow	Green	Blue	Violet	
Maximum recurrent peak reverse voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RWS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current @T _L =75 °C	I _{F(AV)}	0.5							A
Peak forward surge current 8.3ms single half-sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	10.0							A
Maximum instantaneous forward voltage at 0.5 A	V _F	1.2				1.3			V
Maximum DC reverse current @T _A =25°C at rated DC blocking voltage @T _A =125°C	I _R	5.0 50.0							μA
Typical junction capacitance(NOTE 2)	C _J	4.0							pF
Typical reverse recovery time(NOTE3)	t _{rr}	1.5							μS
Typical thermal resistance (NOTE 4)	R _{θJA}	150							°C/W
Operating junction temperature range	T _J	-55-----+150							°C
Storage temperature range	T _{STG}	-55-----+150							°C

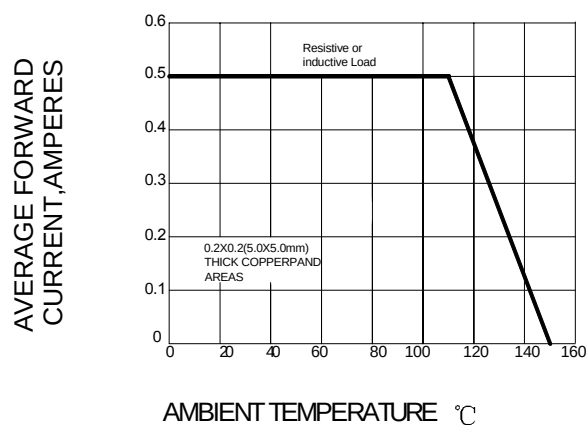
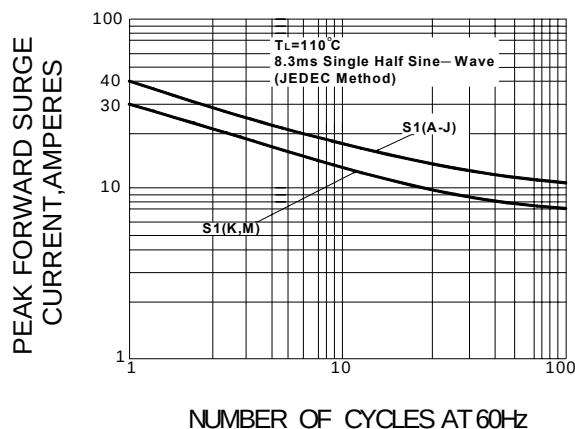
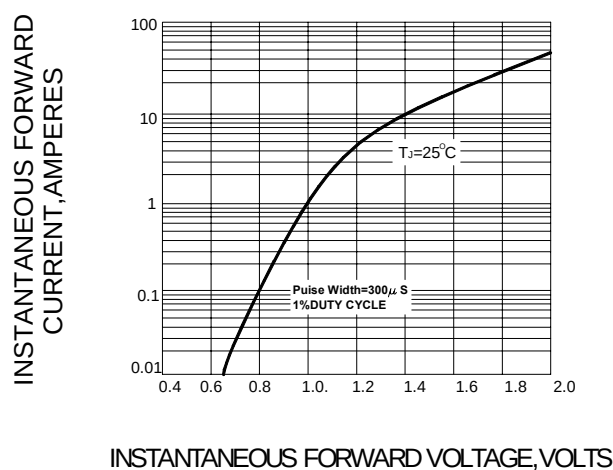
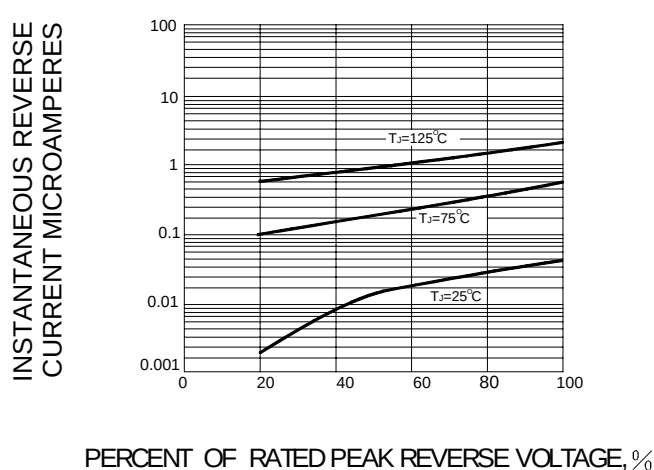
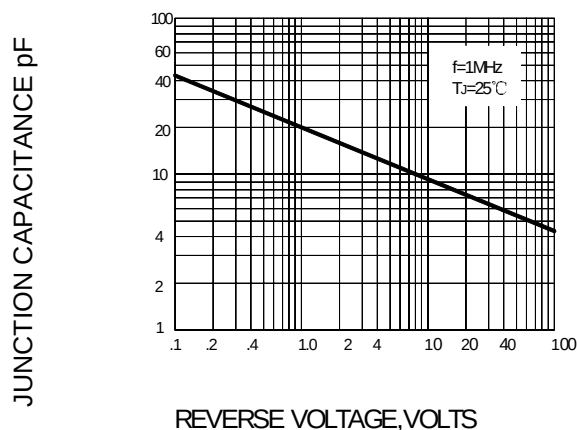
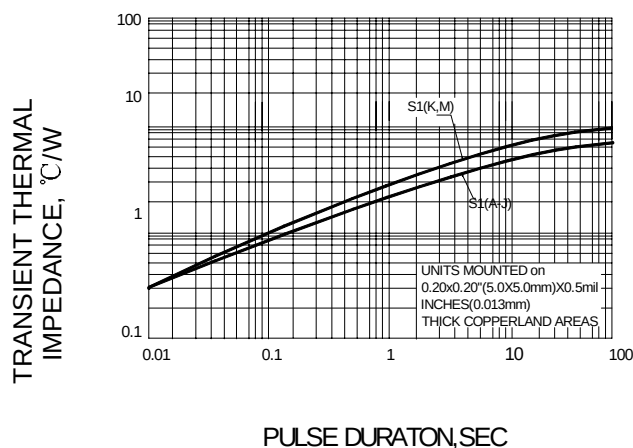
NOTE: 1. Measured at 1.0MHz and applied reverse voltage of 4.0volts

2. Thermal resistance from junction to ambient and junction to lead P.C.B mounted on 0.27"X0.27" (7.0X7.0mm2) copper pad areas

 3. Measured with $I_F = 0.5\text{A}$, $I_R = 1.0\text{A}$, $I_{rr} = 0.25\text{A}$.

4. Thermal resistance from junction to ambient and junction to lead P.C.B. mounted on 0.27"X0.27" (7.0X7.0mm2) copper pad areas

Ratings AND Characteristic Curves

FIG.1 – FORWARD DERATING CURVE

FIG.2 PEAK FORWARD SURGE CURRENT

FIG.3 – TYPICAL FORWARD CHARACTERISTICS

FIG.4 – TYPICAL REVERSE CHARACTERISTICS

FIG.5-TYPICAL JUNCTION CAPACITANCE

FIG.6-TRANSIENT THERMAL IMPEDANCE


PACKAGE	SPQ/PCS	CARTON SPQ/PCS	CARTON SIZE/CM	CARTON GW/KG	CARTON NW/KG
DO-213AA	5000/REEL	80000	36.0X35.8X36.5	18.00	16.00